# **Trench Power MOSFET**

# 12 V, 3.3 A, Single P-Channel, ESD Protected SC-88

#### **Features**

- Leading Trench Technology for Low R<sub>DS(ON)</sub> Extending Battery Life
- SC-88 Small Outline (2x2 mm, SC70-6 Equivalent)
- Gate Diodes for ESD Protection
- Pb-Free Packages are Available

#### **Applications**

- High Side Load Switch
- Cell Phones, Computing, Digital Cameras, MP3s and PDAs

#### MAXIMUM RATINGS (T<sub>J</sub> = 25°C unless otherwise stated)

Param	Symbol	Value	Units			
Drain-to-Source Voltage	$V_{DSS}$	-12	V			
Gate-to-Source Voltage	V <sub>GS</sub>	±12	V			
Continuous Drain	Steady State	T <sub>A</sub> = 25 °C	I <sub>D</sub>	-2.7	Α	
Current (Note 1)		T <sub>A</sub> = 85 °C		-2.0		
	t ≤ 5 s	T <sub>A</sub> = 25 °C		-3.3		
Power Dissipation (Note 1)	Steady State	T <sub>A</sub> = 25 °C	P <sub>D</sub>	0.625	W	
Pulsed Drain Current	I <sub>DM</sub>	-8.0	Α			
Operating Junction and	T <sub>J</sub> , T <sub>STG</sub>	–55 to 150	°C			
Source Current (Body Di	I <sub>S</sub>	-0.8	Α			
Lead Temperature for So (1/8" from case for 10	T <sub>L</sub>	260	°C			

#### THERMAL RESISTANCE RATINGS (Note 1)

Parameter	Symbol	Max	Units
Junction-to-Ambient - Steady State	$R_{\theta JA}$	200	°C/W
Junction-to-Ambient - t ≤ 5 s	$R_{\theta JA}$	141	
Junction-to-Lead - Steady State	$R_{\theta JL}$	102	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

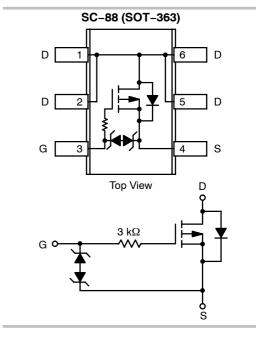
1. Surface mounted on FR4 board using 1 in sq pad size (Cu area = 1.127 in sq [1 oz] including traces).



#### ON Semiconductor®

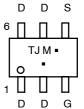
#### http://onsemi.com

V <sub>(BR)DSS</sub>	R <sub>DS(on)</sub> Typ	I <sub>D</sub> Max	
	45 mΩ @ -4.5 V		
-12 V	67 mΩ @ -2.5 V	-3.3 A	
	133 mΩ @ –1.8 V		



# MARKING DIAGRAM & PIN ASSIGNMENT





TJ = Device Code M = Date Code ■ Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

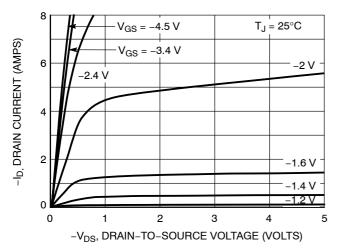
#### **ELECTRICAL CHARACTERISTICS** (T<sub>J</sub>=25°C unless otherwise stated)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain-to-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-12			٧
Drain-to-Source Breakdown Voltage Temperature Coefficient	V <sub>(BR)DSS</sub> /T <sub>J</sub>				10		mV/°C
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>GS</sub> = -9.6 V, V <sub>DS</sub> = 0 V	$V_{GS} = -9.6 \text{ V},$ $V_{DS} = 0 \text{ V}$ $T_{J} = 25^{\circ}\text{C}$ $T_{J} = 125^{\circ}\text{C}$		-2.5	-1.0	μΑ
Gate-to-Source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>G</sub>			-2.5	±1.5	μΑ
date to course Loanage Carrent	1035	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$				±1.0	mΑ
ON CHARACTERISTICS (Note 2)	1	VDS = 0 V, VG	3-112				110 (
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{GS} = V_{DS}, I_{D}$	= 100 μA	-0.40			V
Negative Threshold Temperature Coefficient	V <sub>GS(TH)</sub> /T <sub>J</sub>	GG 557 5			3.4		mV/°C
Drain-to-Source On Resistance	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -3.3 \text{ A}$			45	60	mΩ
		$V_{GS} = -2.5 \text{ V}, I_D = -2.9 \text{ A}$			67	90	
		V <sub>GS</sub> = -1.8 V, I <sub>D</sub> = -1.0 A			133	160	
Forward Transconductance	9FS	$V_{GS} = -10 \text{ V}, I_D = -3.3 \text{ A}$			15		S
CHARGES AND CAPACITANCES			•				
Input Capacitance	C <sub>ISS</sub>				850		pF
Output Capacitance	C <sub>OSS</sub>	$V_{GS} = 0 \text{ V, f} = V_{DS} = -1$	1.0 MHz, 12 V		170		1
Reverse Transfer Capacitance	C <sub>RSS</sub>	- 03			110		1
Total Gate Charge	Q <sub>G(TOT)</sub>				8.6		nC
Gate-to-Source Charge	$Q_{GS}$	$V_{GS} = -4.5 \text{ V}, V_{I}$ $I_{D} = -3.$	<sub>OS</sub> = -5.0 V, 3 A		1.3		7
Gate-to-Drain Charge	$Q_{GD}$	D			2.2		
Gate Resistance	$R_{G}$				3000		Ω
SWITCHING CHARACTERISTICS (No	ote 3)						
Turn-On Delay Time	t <sub>d(ON)</sub>				0.86		μs
Rise Time	t <sub>r</sub>	$V_{GS} = -4.5 \text{ V}, V_{DD} = -6.0 \text{ V},$ $I_{D} = -1.0 \text{ A}, R_{G} = 6.0 \Omega$			1.5		1
Turn-Off Delay Time	t <sub>d(OFF)</sub>				3.5		
Fall Time	t <sub>f</sub>				3.9		
DRAIN-SOURCE DIODE CHARACTE	RISTICS (Note 2	2)					
Forward Diode Voltage	$V_{SD}$	V <sub>GS</sub> = 0 V,	T <sub>J</sub> = 25°C		-0.85	-1.2	٧
		$I_S = -3.3 \text{ Å}$ $T_J = 125^{\circ}\text{C}$		_	-0.7		

Pulse Test: pulse width ≤ 300µs, duty cycle ≤ 2%.
 Switching characteristics are independent of operating junction temperatures.

#### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)

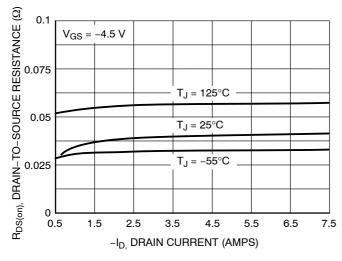
 $V_{DS} \le -12 \text{ V}$ 



O 0.5 1 1.5 2 2.5 3 3.5 4 4.5 -V<sub>GS</sub>, GATE-TO-SOURCE VOLTAGE (VOLTS)

Figure 1. On-Region Characteristics

Figure 2. Transfer Characteristics



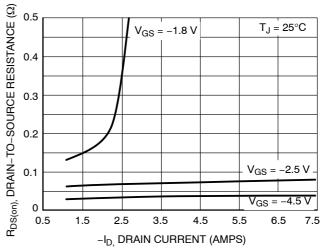


Figure 3. On-Resistance vs. Drain Current and Temperature

Figure 4. On-Resistance vs. Drain Current and Gate Voltage

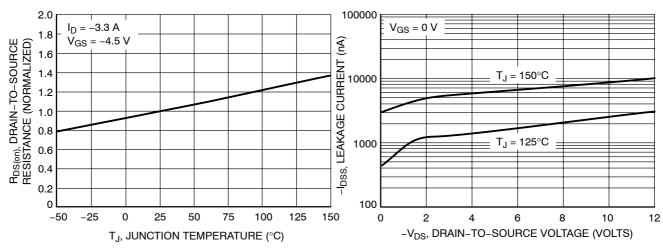
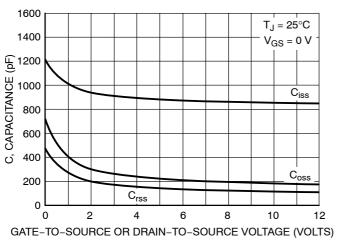


Figure 5. On–Resistance Variation with Temperature

Figure 6. Drain-to-Source Leakage Current vs. Voltage

### TYPICAL PERFORMANCE CURVES (T<sub>J</sub> = 25°C unless otherwise noted)



-V<sub>GS,</sub> GATE-TO-SOURCE VOLTAGE (VOLTS) QT 3.5 3 2.5 Q2 2 Q1 1.5  $I_D = -3.3 A$ 0.5  $T_J = 25^{\circ}C$ 0 6 8 0 10 Qg, TOTAL GATE CHARGE (nC)

Figure 7. Capacitance Variation

Figure 8. Gate-to-Source Voltage vs. Total Gate Charge

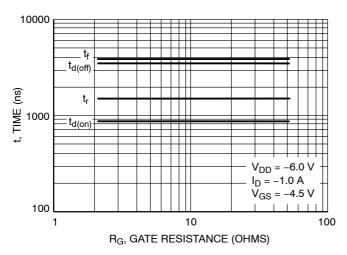


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

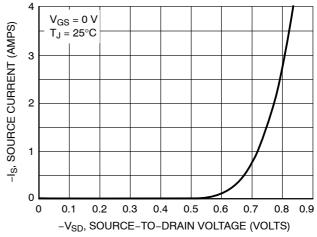


Figure 10. Diode Forward Voltage vs. Current

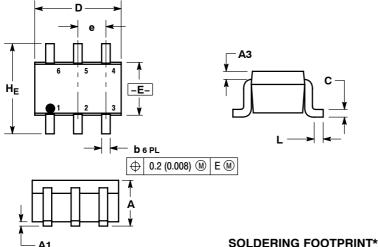
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>		
NTJS3151PT1	SC-88	3000 Tape & Reel		
NTJS3151PT1G	SC-88 (Pb-Free)	3000 Tape & Reel		
NTJS3151PT2	SC-88	3000 Tape & Reel		
NTJS3151PT2G	SC-88 (Pb-Free)	3000 Tape & Reel		

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

#### SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE W**



#### NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
- 419B-01 OBSOLETE, NEW STANDARD 419B-02.

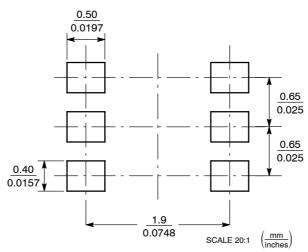
		MILLIMETERS			INCHES			
	DIM	MIN	NOM	MAX	MIN	NOM	MAX	
[	Α	0.80	0.95	1.10	0.031	0.037	0.043	
[	A1	0.00	0.05	0.10	0.000	0.002	0.004	
	АЗ	0.20 REF			0.008 REF			
	b	0.10	0.21	0.30	0.004	0.008	0.012	
[	С	0.10	0.14	0.25	0.004	0.005	0.010	
	D	1.80	2.00	2.20	0.070	0.078	0.086	
	Е	1.15	1.25	1.35	0.045	0.049	0.053	
ſ	е	0.65 BSC			0.026 BSC			
[	L	0.10	0.20	0.30	0.004	0.008	0.012	
ſ	He	2.00	2.10	2.20	0.078	0.082	0.086	

#### STYLE 28:

- PIN 1. DRAIN 2. DRAIN

  - 3. GATE 4. SOURCE

  - 5. DRAIN 6. DRAIN



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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